ABSTRACT
This document describes the differences between a bq20z70/bq20z75 design and a bq20z40/bq20z45 solution. Find the latest ordering information and data sheet on the World Wide Web at: http://power.ti.com.

Introduction
The bq20z40/bq20z45 firmware has been released to enable several feature additions and improvements over the bq20z70/bq20z75. The bq20z40/bq20z45 devices are pin and footprint compatible with the bq20z70/bq20z75 devices for easy hardware upgrade.

Orderable part numbers for new devices are:
- bq20z40DBT
- bq20z40DBTR
- bq20z45DBT
- bq20z45DBTR

The latest version of the TI evaluation software is required to be able to read and write all the data flash configuration locations. The updated evaluation software can be obtained at http://power.ti.com.

Change Details

<table>
<thead>
<tr>
<th>#</th>
<th>CHANGE</th>
<th>bq20z40/bq20z45</th>
<th>bq20z70/bq20z75</th>
<th>COMMENTS</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>Added enhanced charging algorithm (satisfies JEITA specification) temperature ranges</td>
<td>Satisfies JEITA temperature range guidelines.</td>
<td>Does not satisfy JEITA temperature range guidelines.</td>
<td>Increased temperature safety</td>
</tr>
<tr>
<td>2</td>
<td>Charging voltage and charging current vary with enhanced charging algorithm (satisfies JEITA specification) temperature range</td>
<td>Can specify different charging voltages and charging currents for each temperature range.</td>
<td>Charging voltage is the same, except for the data flash name; charging current is different in pre-charge mode and during temp. throttling.</td>
<td>Improves safety and potential for increased cell life</td>
</tr>
<tr>
<td>3</td>
<td>Cell overvoltage thresholds vary with temperature range.</td>
<td>Can specify different cell overvoltage thresholds (1st - level and permanent failure) for each temperature range (this is part of the enhanced charging algorithm).</td>
<td>Only one cell overvoltage threshold. Only one PF overvoltage threshold, which is pack based rather than cell based.</td>
<td>Allows for enhanced customization and improves safety</td>
</tr>
<tr>
<td>4</td>
<td>Safety undervoltage 2nd level protection</td>
<td>Monitors the individual cell voltages for extreme undervoltage values (this is part of the enhanced charging algorithm).</td>
<td>Feature is not supported.</td>
<td>Improves safety</td>
</tr>
<tr>
<td>5</td>
<td>Added a discharge inhibit mode</td>
<td>If the temperature of the battery is too high, then the battery will not be allowed to start discharging.</td>
<td>Feature is not supported.</td>
<td>Improves safety</td>
</tr>
<tr>
<td>#</td>
<td>CHANGE</td>
<td>bq20z40/bq20z45</td>
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</tr>
<tr>
<td>6</td>
<td>Cell deterioration capacity limits and flags</td>
<td>Can specify warning and fault limits for reduced cell capacity as well as a cell life limit with flags to indicate each condition (this is part of the enhanced charging algorithm).</td>
<td>Feature is not supported.</td>
<td>Improves safety and provides more detailed battery information</td>
</tr>
<tr>
<td>7</td>
<td>Relative State of Charge (RSOC) improvements</td>
<td>Implements Impedance Track™ changes to improve RSOC performance. Added Load Select 7 (see SLUUS13 for a description) which helps to improve Impedance Track™ accuracy.</td>
<td>Feature is not supported.</td>
<td>Improves gauging accuracy</td>
</tr>
<tr>
<td>8</td>
<td>Lifetime data</td>
<td>Lifetime data is recorded and is accessible through data flash or by using an extended SBS command.</td>
<td>Very limited lifetime data. Only accessible through data flash.</td>
<td>Improves data logging and troubleshooting capability</td>
</tr>
<tr>
<td>9</td>
<td>Manufacturer Data</td>
<td>Added 4 additional 19 byte data flash locations for storing manufacturing data (DF:Manuf. Block 1..4). Manuf. Info 0 is still 31 bytes long. There is now a total of 107 bytes of Manufacturing Info storage.</td>
<td>Only has 31 byte Manuf. Info 0.</td>
<td>Provides enhanced customization and data storage</td>
</tr>
<tr>
<td>10</td>
<td>Permanent Fail status</td>
<td>Because of the addition of new permanent failure modes: one status and two status logging registers were added. SBS.PF Status 2 was added for status. DF:Saved PF Flags 2 and DF:Saved 1st PF Flags 2 was added for logging.</td>
<td>Only has 1 PF Status failure register and 2 logging registers.</td>
<td>Added to support new safety features (see change 4, 11, and 12)</td>
</tr>
<tr>
<td>11</td>
<td>Cell imbalance detection methods</td>
<td>Supports 2 mechanisms for cell imbalance detection: Active and at Rest with independent flags</td>
<td>Supports cell imbalance detection at Rest only</td>
<td>Improves safety</td>
</tr>
<tr>
<td>12</td>
<td>Independent temperature alarms for 2nd thermistor</td>
<td>Separate OTC, OTD, SOTC, and SOTD alarms and thresholds for TS1 and TS2</td>
<td>Only one set of alarms and thresholds</td>
<td>Improves safety and design customization</td>
</tr>
<tr>
<td>13</td>
<td>Ability to go to sleep without calibration</td>
<td>Enters sleep mode immediately when sleep command is received without performing calibration first (improves efficiency during manufacturing)</td>
<td>Calibration is always performed upon entry to sleep.</td>
<td>Improves efficiency during manufacturing</td>
</tr>
<tr>
<td>14</td>
<td>PF Fuse Blow features</td>
<td>New PF Fuse Blow features added. DF:PF SOV Fuse Blow Delay determines the length of time after a PF SOV event occurs before the fuse is blown. DF:PF Min Fuse Blow Voltage requires the battery be above this threshold before the fuse is blown.</td>
<td>Features are not supported.</td>
<td>Improves safety</td>
</tr>
<tr>
<td>15</td>
<td>Seal delay option added after sealing gauge</td>
<td>The DF-Sealed Ship Delay timer introduces a programmable delay before shutting off the FETs for ship mode after the seal commands are sent to the gauge.</td>
<td>Feature is not supported.</td>
<td>Adds convenience during production</td>
</tr>
</tbody>
</table>
Summary

The following is a list of new data flash and SBS parameters added to bq20z40/bq20z45, sorted by table item. Descriptions can be found in the technical reference user's guide (SLUU313):

1. Added enhanced charging algorithm temperature ranges
   - DF:JT1
   - DF:JT2
   - DF:JT2a
   - DF:JT3
   - DF:JT4
   - **SBS:TempRange (0x72)**

2. Charging voltage and charging current vary with enhanced charging algorithm temperature range
   - DF:LT Chg Voltage
   - DF:LT Chg Current1
   - DF:LT Chg Current2
   - DF:LT Chg Current3
   - DF:ST1 Chg Voltage
   - DF:ST1 Chg Current1
   - DF:ST1 Chg Current2
   - DF:ST1 Chg Current3
   - DF:ST2 Chg Voltage
   - DF:ST2 Chg Current1
   - DF:ST2 Chg Current2
   - DF:ST2 Chg Current3
   - DF:HT Chg Voltage
   - DF:HT Chg Current1
   - DF:HT Chg Current2
   - DF:HT Chg Current3
   - DF:Cell Voltage Threshold1
   - DF:Cell Voltage Threshold2
   - DF:Cell Voltage Thresh Hys

3. Cell overvoltage thresholds vary with temperature range
   - DF:LT COV Threshold
   - DF:LT COV Recovery
   - DF:ST COV Threshold
   - DF:ST COV Recovery
   - DF:HT COV Threshold
   - DF:HT COV Recovery
   - DF:LT SOV Threshold
   - DF:ST SOV Threshold
   - DF:HT SOV Threshold

4. Safety undervoltage 2nd level protection
   - DF:SUV Threshold
   - DF:SUV Time

5. Added a discharge inhibit mode
   - DF:Hi Dsg Start Temp

6. Cell deterioration capacity limits and flags
   - DF:Deterioration Warn Limit
• DF:Deterioration Fault Limit
• DF:Cell Life Limit
7. Relative State of Charge (RSOC) improvements
• [OCV_WGHT] in DF:Operation Cfg C
• Option 7 in DF:Load Select
8. Lifetime data
• DF:Lifetime Max Cell Voltage
• DF:Lifetime Min Cell Voltage
• DF:Lifetime Max Pack Voltage
• DF:Lifetime Min Pack Voltage
• DF:Lifetime Max Chg Current
• DF:Lifetime Max Dsg Current
• DF:Lifetime Max Chg Power
• DF:Lifetime Max Dsg Power
• DF:Life Max AvgDsg Cur
• DF:Life Max AvgDsg Pow
• DF:Life Avg Temp
• SBS:LifetimeData (0x73)
9. Manufacturer Data
• DF:Manuf. Block 1
• DF:Manuf. Block 2
• DF:Manuf. Block 3
• DF:Manuf. Block 4
• SBS:ManufBlock1..4 (0x6c..0x6f)
10. Permanent Fail status
• DF:Permanent Fail Cfg 2
• DF:Saved PF Flags 2
• DF:Saved 1st PF Flags 2
• SBS:PFStatus2 (0x6b)
11. Cell imbalance detection methods
• DF:Rest CIM Current
• DF:Rest CIM Fail Voltage
• DF:Rest CIM Time
• DF:CIM Battery Rest Time
• DF:Rest CIM Check Voltage
• DF:Active CIM Fail Voltage
• DF:Active CIM Time
• DF:Active CIM Check Voltage
12. Independent temperature alarms for 2nd thermistor
• DF:OT2 Chg Threshold
• DF:OT2 Chg Time
• DF:OT2 Chg Recovery
• DF:OT2 Dsg Threshold
• DF:OT2 Dsg Time
• DF:OT2 Dsg Recovery
• DF:SOT2 Chg Threshold
• DF:SOT2 Chg Time
• DF:SOT2 Dsg Threshold
• DF:SOT2 Dsg Time
• SBS:TS1Temperature (0x5e)
• SBS:TS2Temperature (0x5f)
• SBS:SafetyStatus2 (0x69)

14. PF Fuse Blow features
• DF:PF SOV Fuse Blow Delay
• DF:PF Min Fuse Blow Voltage

15. Seal delay option added after sealing gauge
• DF:Sealed Ship Delay
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